



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Leung, M.S.  
Serial No. 10/666,399  
Filed: Sept. 18, 2003  
Docket No. P0298US-7

Confirmation No. 8955  
Examiner: Le, Thao X.  
Art Unit: 2814  
Customer No. 23935

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AND RESPONSE**

Sir:

In response to the Office Action mailed on February 28, 2006, please amend the above-identified application as follows:

**AMENDMENTS TO THE SPECIFICATION** begin on page 2 of this paper.

**AMENDMENTS TO THE CLAIMS** are reflected in the listing of claims which begin on page 7 of this paper.

**REMARKS AND ARGUMENTS** begin on page 15 of this paper.